

**Product / Package Information**

Package	TSSOP_4.4_EP
Body Size	4.4 mm
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS010727B

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.92E-02	86.91	869100	49.52	495230
Thermosets	Epoxy & Phenol Resin	Proprietary	4.29E-03	12.78	127800	7.28	72823
Other inorganic materials	Carbon black	1333-86-4	1.04E-04	0.31	3100	0.18	1766
Subtotal			3.36 E-02	100.00	1000000	56.98	569819

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.83 E-02	96.20	962000	30.99	309883
Copper & its alloys	Nickel	7440-02-0	5.69 E-04	3.00	30000	0.97	9664
Copper & its alloys	Silicon	7440-21-3	1.23 E-04	0.65	6500	0.21	2094
Copper & its alloys	Magnesium	7439-95-4	2.85 E-05	0.15	1500	0.05	483
Subtotal			1.90 E-02	100.00	1000000	32.21	322123

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.90 E-04	100.0	1000000	0.32	3221

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.26 E-03	100.0	1000000	2.14	21423

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.59 E-04	100.0	1000000	0.95	9494

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.00 E-03	100.0	1000000	5.09	50862

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.06 E-03	77.71	777100	1.79	17918
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	4.22 E-05	3.11	31100	0.07	717
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	4.22 E-05	3.11	31100	0.07	717
Other organic materials	Butyrolactone, gamma-	96-48-0	4.22 E-05	3.11	31100	0.07	717
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	4.22 E-05	3.11	31100	0.07	717
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.22 E-05	3.11	31100	0.07	717
Other organic materials	Organosilane	TS ref# 10001	4.22 E-05	3.11	31100	0.07	717
Other inorganic materials	Copper(II) oxide	1317-38-0	4.22 E-05	3.11	31100	0.07	717
Other organic materials	Epoxy resin modifier	TS ref# 10038	7.06 E-06	0.52	5200	0.012	120
Subtotal			1.36 E-03	100.0	1000000	2.31	23057

<b>Package Totals</b>			<b>Weight (g)</b> 5.89 E-02			<b>Percentage (%)</b> 100	<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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